

**UL** 60950 (File No.E108430)

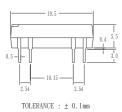
#### **Features**

- 1. Molded epoxy body.
- 2. Dip type construction with the same terminal pitch as ICs or TTLs simplifies PC board designing. In addition, the high sensitivity allows direct driving by TTL, etc.
- 3. Automatic insertion compatible.
- 4. Sealed construction permits automatic flow soldering and cleaning.
- 5. Diode & Magnetic shield are available.

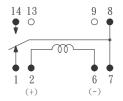
### **Outside Dimension: Unit (mm)**







## **Schematic:Top View**



# **Coil Ratings**

(AT 20°C)

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Parameter	Rating	Unit
Coil Resistance	2150	Ω(±10%)
Nominal Coil Voltage	24	VDC
Maximun Continuous Voltage	28	VDC
Must Operate	18	VDC
Must Release	2.4	VDC
Rated Current	11.1	mA

#### **Electrical Characteristics**

Parameter	Rating	Unit
Contact Resistance	150	mΩ (max)
Operate Time	1.0	ms(max)
Bounce Time	2.0	ms(max)
Release Time	1.0	ms(max)
Insulation Resistance (100VDC)	10 <sup>9</sup>	$\Omega$ (min)
Power	3	VA(max)
Switching Voltage	100	VDC(max)
Switching Current	0.25	A(max)
Carry Current	0.5	A(max)
Breakdown Voltage ( Across Open Contact )	200	VDC(min)
( Between Coil & Contact )	500	VDC(min)
Life Expectancy (Signal Level)	5 x 10 <sup>7</sup>	
Operating Temp	-40 to 85	°C
Storage Temp	-50 to125	°C
Resonant Frequency	3.5	KHZ
Vibration ( 10-2000HZ )	20	g(max)
Minimum Permissible Load	100	mVDC 10μA